



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

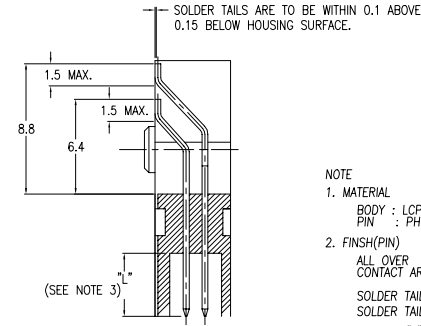
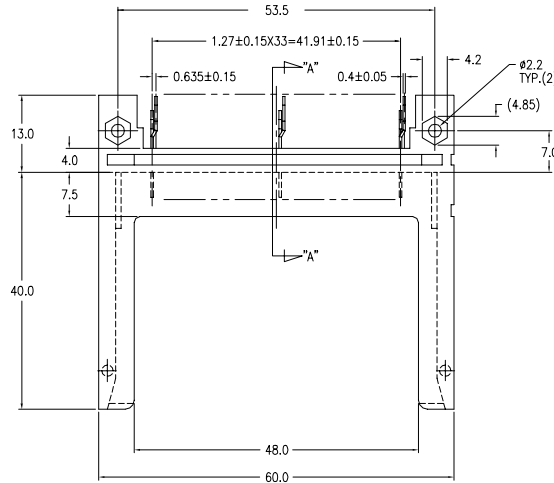
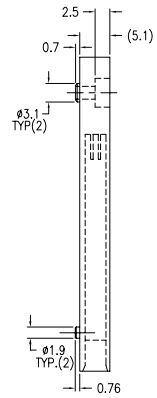
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PRODUCT No.
90937-001
90937-001LF

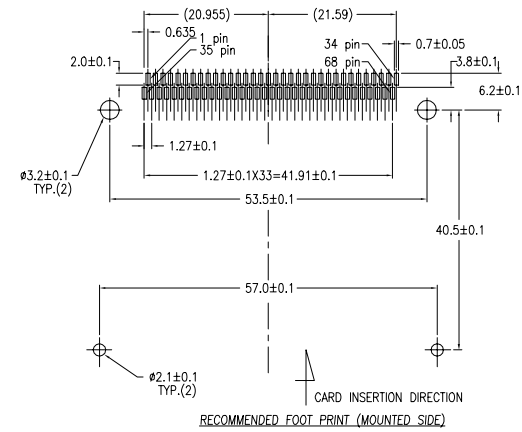
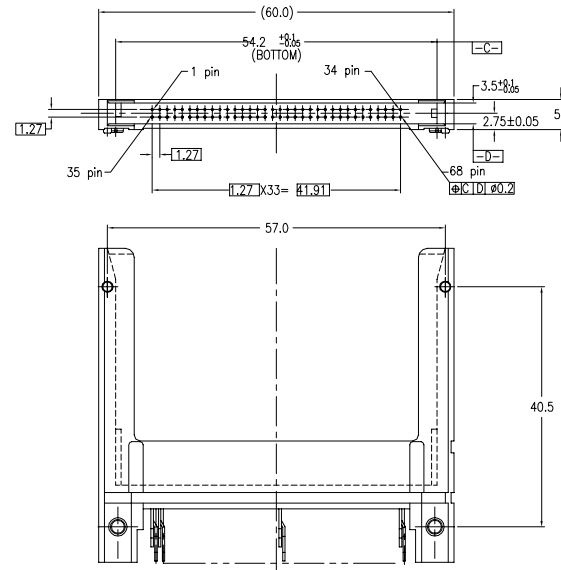


SECTION "A-A" (5/1)

NOTE

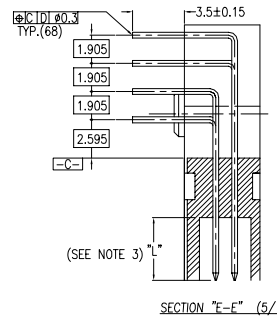
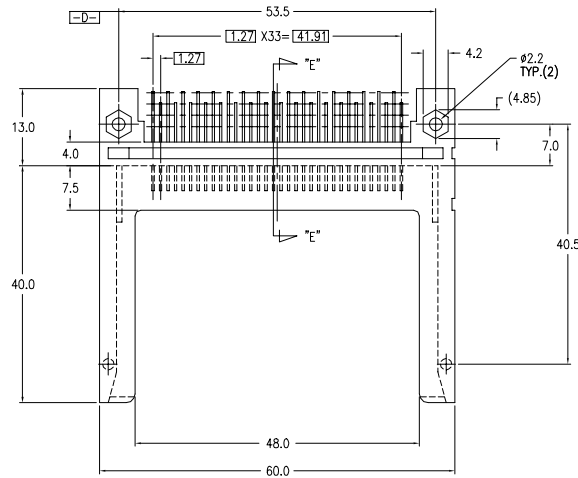
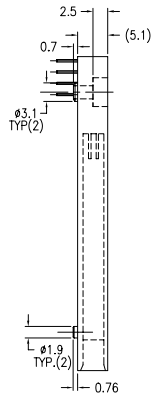
- MATERIAL
BODY : LCP UL94V-0 BLACK
PIN : PHOSPHOR BRONZE
- FINSH(PIN)
ALL OVER : Ni UNDER PLATING 0.5um THK MIN.
CONTACT AREA : Au 0.1um THK MIN.
OVER P2/N2 0.5um THK MIN.
SOLDER TAIL(Tin Lead option) : Sn/Pd 2.5um THK MIN.
SOLDER TAIL(Lead free option) : Pure Tin 2.5um THK MIN.
- DIMENSION "L"

1,17,34,35,51,68PIN	5.0±0.1
36,67PIN	3.5±0.1
OTHERS	4.25±0.1
- CARD SLOT AND PIN DIMENSIONS PER JEIDA/PCMCIA STANDARDS
- IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N,THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION



mat'l. code		surface		tolerance		projection		product family	
		ISO1302		ISO1101 ISO406				MCS	
l t r e c n n o d r		date		tolerances unless otherwise specified		MM		title	
A J30167 KS		6/1/'93		±0.3		scale 2:1		68POS. HEADER ASS'Y	
B N06-0031 MZ		03/08/06		0°±2'				JEIDA / PCMCIA TYPE I,II	
C ELX-N-011427 ZK		04/23/12						sheet 1 of 4	
				dr S.Ohmori		6/1/'93		dwg no	
				enr S.Ohmori		6/1/'93		90937	
				chr S.Ohmori		6/1/'93		A4	
				appd S.Ohmori		6/1/'93		type Product Customer Drawing	
sheet index	revision sheet	c	c	c	c				
	1	2	3	4					

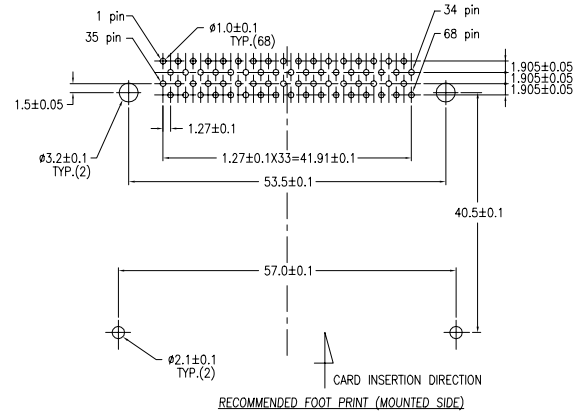
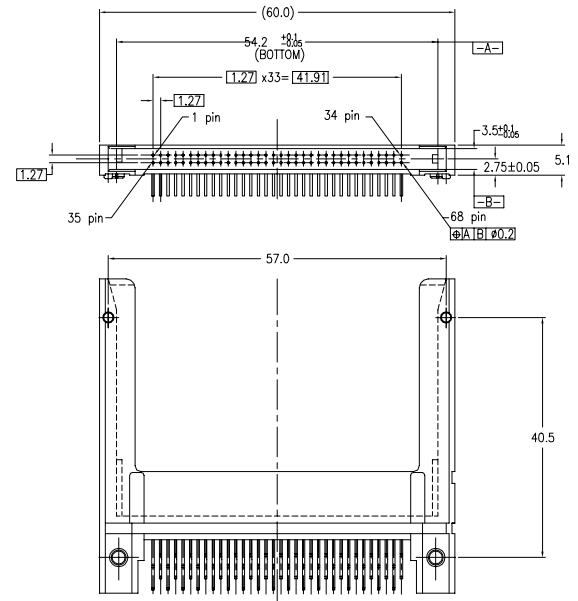
PRODUCT No.
90937-002
90937-002LF



NOTE

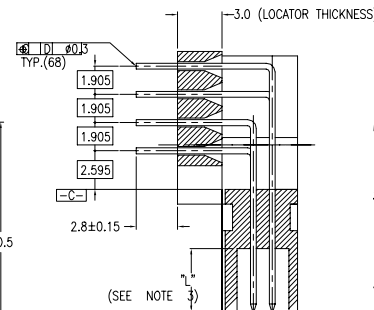
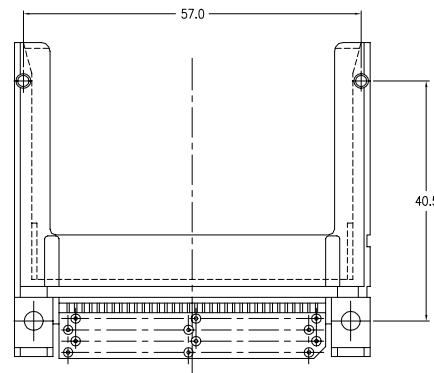
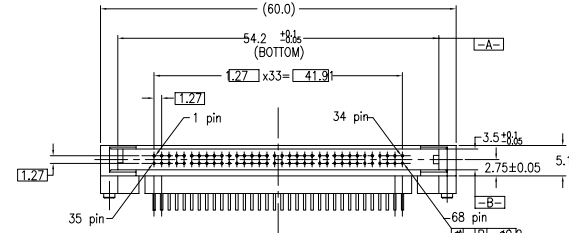
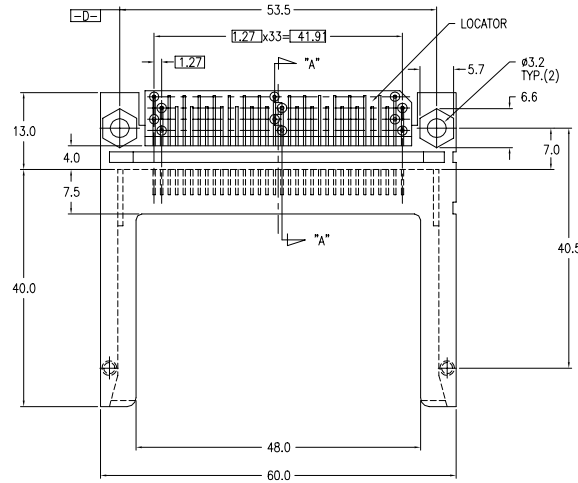
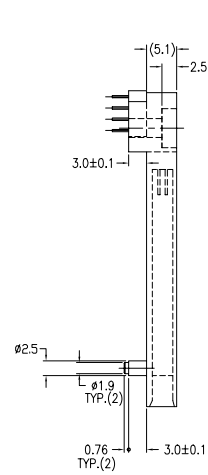
- MATERIAL
BODY : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE
- FINISH(PIN)
ALL OVER : Ni UNDER PLATING 0.5µm THK MIN.
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL(Tin Lead option) : Sn/Pb 2.5µm THK MIN.
SOLDER TAIL(Lead free option) : Pure Tin 2.5µm THK MIN.
- DIMENSION "L"

1,17,34,35,51,68PIN	5.0±0.1
36,67PIN	3.5±0.1
OTHERS	4.25±0.1
- CARD SLOT AND PIN DIMENSIONS
PER JEIDA/PCMCIA STANDARDS
- IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N,THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC:110-263



mat'l. code	surface ISO1302	tolerance ISO1101 ISO406	projection	product family MCS
ltr ecn nodr date	tolerances unless otherwise specified		MM	title 68POS. HEADER ASS'Y JEIDA / PCMCIA TYPE I,II
c	angle 0°±2'	±0.3	scale 2:1	sheet 2 of 4 size A4
	dr S.Ohmori	6/1/'93		dwg no 90937
	engr S.Ohmori	6/1/'93		type Product Customer Drawing
	chr S.Ohmori	6/1/'93		
sheet index	revision sheet			

PRODUCT No.
90937-013
90937-013LF

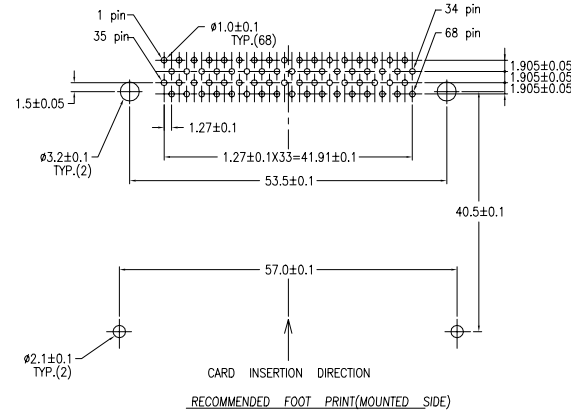


SECTION "A-A" (5/1)

NOTE

- MATERIAL
BODY : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE
- FINISH(PIN)
ALL OVER : Ni UNDER PLATING 0.5um THK MIN.
CONTACT AREA : 0.076 µm MIN. GOLD
SOLDER TAIL(Tin Lead option) : Sn/Pb 2.5um THK MIN.
SOLDER TAIL(Lead free option) : Pure Tin 2.5um THK MIN.
- DIMENSION "L"

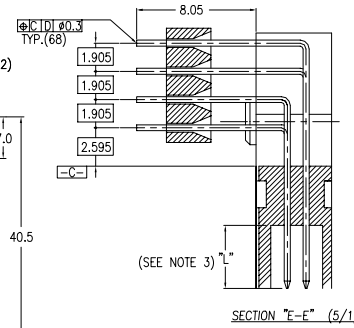
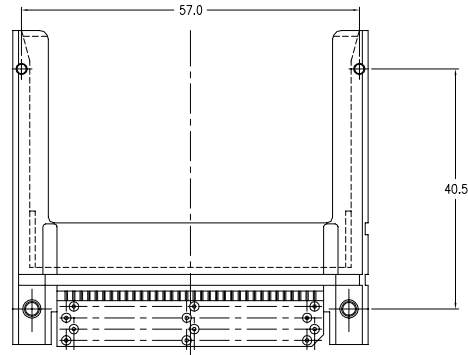
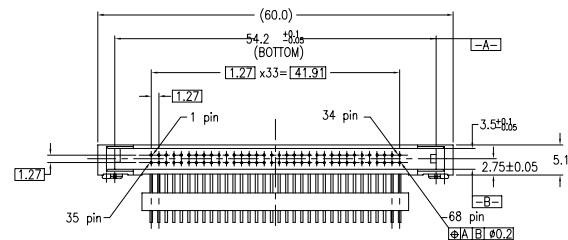
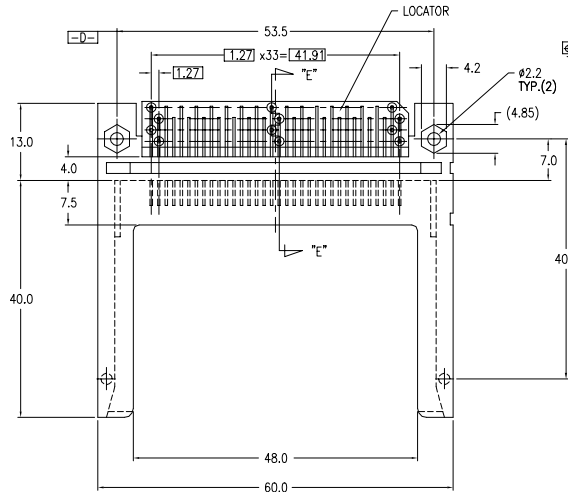
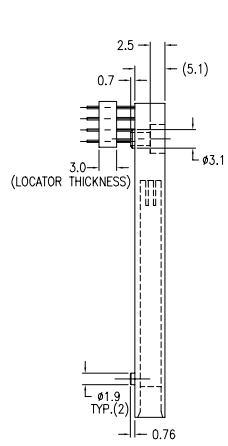
1,17,34,35,51,68PIN	5.0±0.1
36,67PIN	3.5±0.1
OTHERS	4.25±0.1
- CARD SLOT AND PIN DIMENSIONS PER JEIDA/PCMCIA STANDARDS
- IF LEAD FREE P/N,THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N,THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- PRODUCT SPEC:110-263



mat'l. code	surface	tolerance	projection	product family
	ISO1302	ISO1101 ISO406		MCS
l t r e c n n o d r	date	tolerances unless otherwise specified	scale	title
			MM	68POS. HEADER ASS'Y
		angle	scale 2:1	JEIDA / PCMCIA TYPE I,II
		0°±2'		dwg no
	dr	S.Ohmori	6/1/'93	sheet 3 of 4
	engr	S.Ohmori	6/1/'93	size
	chr	S.Ohmori	6/1/'93	A4
	appd	S.Ohmori	6/1/'93	type
sheet index	revision sheet			Product Customer Drawing

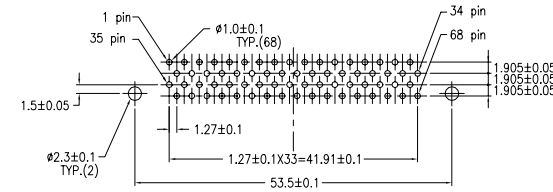


PRODUCT No.
90937-003
90937-003LF



- NOTE
- MATERIAL
BODY : HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
PIN : PHOSPHOR BRONZE
 - FINISH(PIN)
ALL OVER : Ni UNDER PLATING 0.5um THK MIN.
CONTACT AREA : 0.076 um MIN. GOLD
SOLDER TAIL(Tin Lead option) : Sn/Pb 2.5um THK MIN.
SOLDER TAIL(Lead free option) : Pure Tin 2.5um THK MIN.
 - DIMENSION "L"

1,17,34,35,51,68PIN	5.0±0.1
36,67PIN	3.5±0.1
OTHERS	4.25±0.1
 - CARD SLOT AND PIN DIMENSIONS PER JEIDA/PCMCIA STANDARDS
 - IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
 - IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBED IN GS-22-008
 - LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
 - PRODUCT SPEC:110-263



CARD INSERTION DIRECTION
RECOMMENDED FOOT PRINT (MOUNTED SIDE)

mat'l. code	surface	tolerance	projection	product family
	ISO1302	ISO1101 ISO406		MCS
l t r e c n n o d r	date	tolerances unless otherwise specified	MM	title
c		angle	scale 2:1	68POS. HEADER ASS'Y
		0°±2'		JEIDA / PCMCIA TYPE I,II
	dr	S.Ohmori		sheet 4 of 4
	enr	S.Ohmori		size
	chr	S.Ohmori		A4
	appd	S.Ohmori		type Product Customer Drawing
sheet index	revision sheet			